

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5611	(semiconductor or ic or die or chip or (integrated adj circuit)) and (scribe near3 line)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 18:20
L2	1216	1 and (resin or encapsulant or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 18:22
L3	1204	257/668.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:21
L4	489	257/670.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:21
L5	706	257/680.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:21
L6	1706	257/690.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:21
L7	1658	257/738.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:21
L8	1280	257/780.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:21

L10	1996	257/784.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:22
L11	1561	257/777.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:21
L12	2476	257/778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:21
L13	502	257/702.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:21
L14	741	257/703.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:21
L15	11174	3 4 5 6 7 8 10 11 12 13 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:22
L16	184	15 and (scribe near3 line)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 18:58
S1	1	("6677219").PN.	USPAT	OR	OFF	2005/01/09 12:14
S2	1	("6300685").PN.	USPAT	OR	OFF	2005/01/09 12:14
S3	2	S1 S2	USPAT	OR	OFF	2005/01/09 12:20
S4	1	"6013948".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:15
S5	1	"5976916".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:15

S6	1	"5956233".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:15
S7	1	"5864174".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:15
S8	1	"5793104".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:15
S9	1	"5793104".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:15
S10	1	"5777391".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:15
S11	1	"6242283".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S12	1	"6207477".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S13	1	"6013948".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S14	1	"5976916".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S15	1	"5956233".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S16	1	"5950070".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S17	1	"5864174".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S18	1	"5858815".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S19	1	"5793104".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S20	1	"5777391".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S21	1	"5627408".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S22	1	"5394009".PN.	USPAT; USOCR	OR	OFF	2005/01/09 12:18
S23	12	S4 S5 S6 S7 S8 S9 S10 S11 S12 S13 S14 S15 S16 S17 S18 S19 S20 S21 S22	USPAT	OR	OFF	2005/01/09 12:28
S24	1173	257/668.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/20 18:20

S25	474	257/670.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 12:29
S26	665	257/680.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 13:00
S27	1615	257/690.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 13:14
S28	1521	257/738.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 13:14
S29	1182	257/780.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 13:14
S30	1873	257/784.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 13:15
S31	1419	257/777.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 13:15
S32	2286	257/778.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 13:15

S33	483	257/702.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 13:15
S34	965	257/783.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 13:15
S35	10442	S24 S25 S26 S27 S28 S29 S30 S31 S32 S33 S34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/09 13:15
S36	173	S35 and (scribe near3 line)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 18:22
S37	5234	(semiconductor or ic or die or chip or (integrated adj circuit)) and (scribe near3 line)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 18:20
S38	1090	S37 and (resin or encapsulant or epoxy)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 18:20
S39	961	S38 not S36	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 13:36
S40	1	("20040094833").PN.	US-PGPUB; USPAT	OR	OFF	2005/01/09 15:51